

Electronic Patent Application Fee Transmittal

Application Number:	10612281			
Filing Date:	30-Jun-2003			
Title of Invention:	Bond finger on via substrate, process of making same, package made thereby, and method of assembling same			
First Named Inventor:	Brian Taggart			
Filer:	Joseph P. Mehrle/Anne Richards			
Attorney Docket Number:	884.853US1			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	500	500
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				500